



SSC8522GSG

Dual N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
20V	$\pm 12V$	210m Ω @4.5V	0.9A
		240m Ω @2.5V	
		290m Ω @1.8V	

➤ Description

This device is N-Channel enhancement MOSFET. Uses Trench technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

➤ Applications

- Motor Drive Control
- Portable Devices
- DCDC Conversion
- Power Supplies

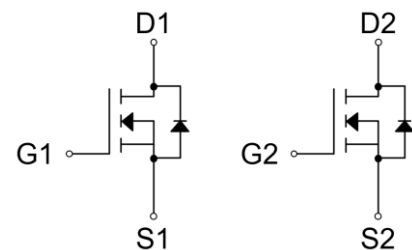
➤ Ordering Information

Device	Package	Shipping
SSC8522GSG	SOT-363	3000/Reel

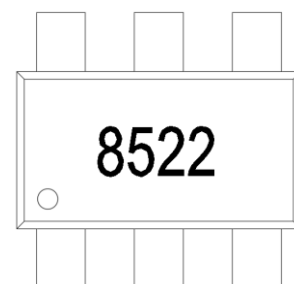
➤ Pin Configuration



SOT-363 (Top View)



Pin Configuration



Markin



➤ **Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain-to-Source Voltage		20	V
V_{GSS}	Gate-to-Source Voltage		± 12	V
I_D	Continuous Drain Current ^a	$T_A=25^{\circ}\text{C}$	0.9	A
		$T_A=100^{\circ}\text{C}$	0.5	
I_{DM}	Pulsed Drain Current ^b		3.6	A
P_D	Power Dissipation ^a	$T_A=25^{\circ}\text{C}$	0.27	W
		$T_A=100^{\circ}\text{C}$	0.11	
T_J	Operation junction temperature		-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55~150	

➤ **Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	459	$^{\circ}\text{C}/\text{W}$

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.

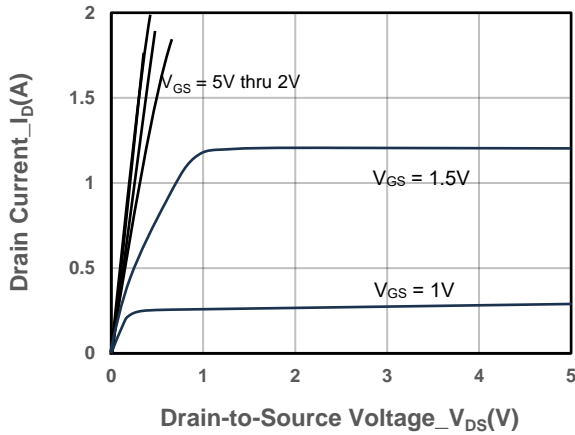


➤ **Electrical Characteristics (T_A=25°C unless otherwise noted)**

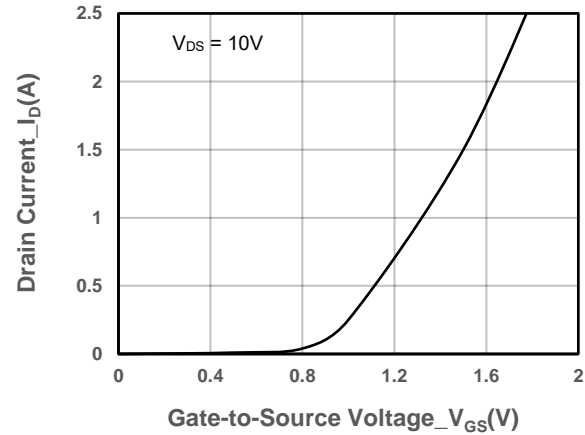
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.35	0.65	1	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 0.5A		210	380	mΩ
		V _{GS} = 2.5V, I _D = 0.5A		240	450	mΩ
		V _{GS} = 1.8V, I _D = 0.35A		290	800	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±10	uA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 0.15A			1.2	V
Input Capacitance	C _{ISS}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz		63		pF
Output Capacitance	C _{OSS}			37		
Reverse Transfer Capacitance	C _{RSS}			22		
Total Gate Charge	Q _G	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 0.5A		1.3		nC
Gate to Source Charge	Q _{GS}			0.28		
Gate to Drain Charge	Q _{GD}			0.23		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 0.5A, R _G = 6Ω		4.1		ns
Rise Time	T _r			2.7		
Turn-off Delay Time	T _{D(OFF)}			13.4		
Fall Time	T _f			5.5		
Diode Recovery Time	T _{rr}	I _F =0.5A, di/dt=100A/us		14		ns
Diode Recovery Charge	Q _{rr}	I _F =0.5A, di/dt=100A/us		10		nC



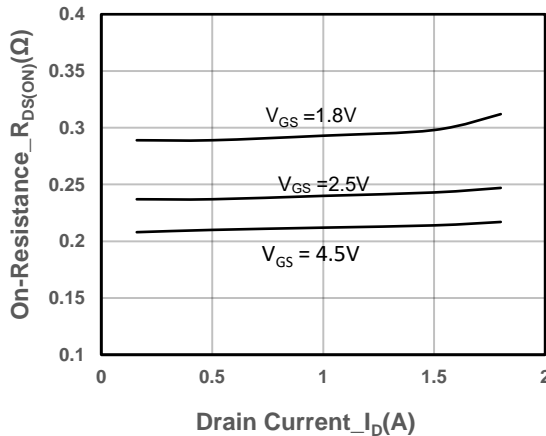
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



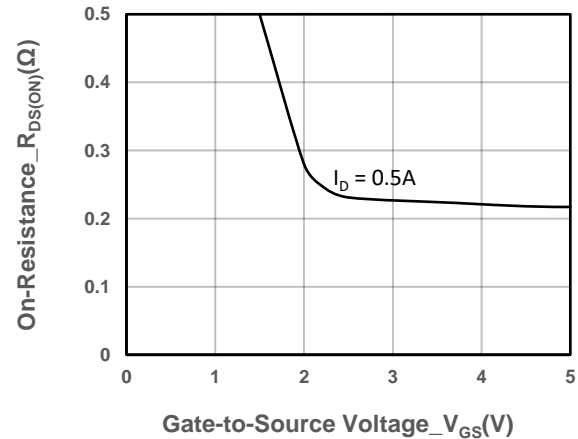
Output Characteristics



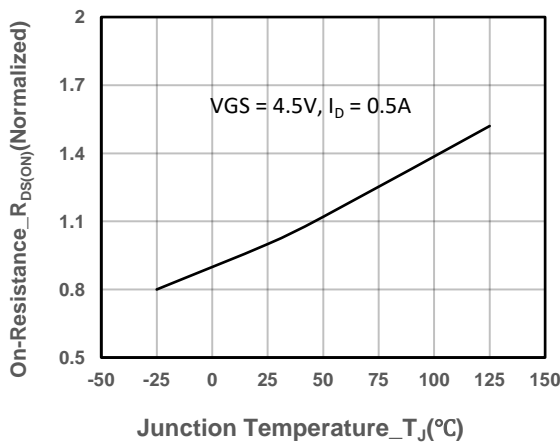
Transfer Characteristics



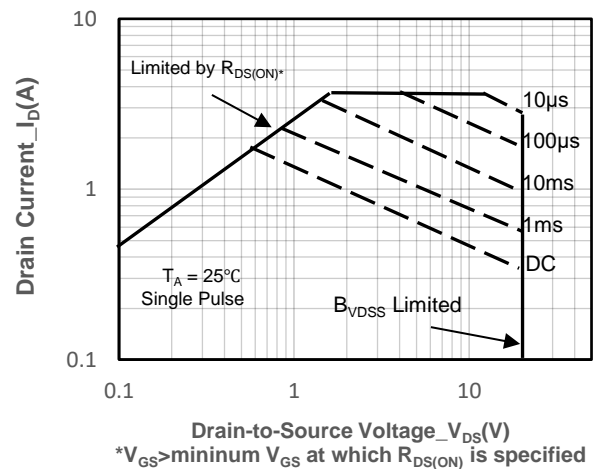
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage



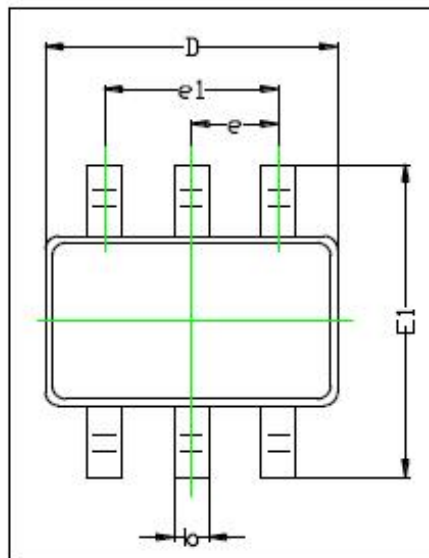
On-Resistance vs. Junction Temperature



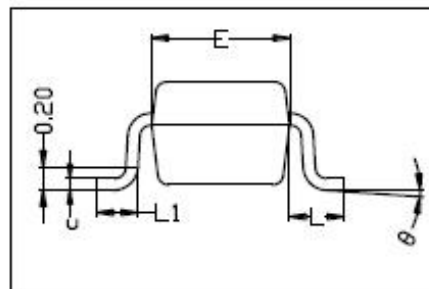
Safe Operating Area vs. Junction-to-Ambient

➤ Package Information

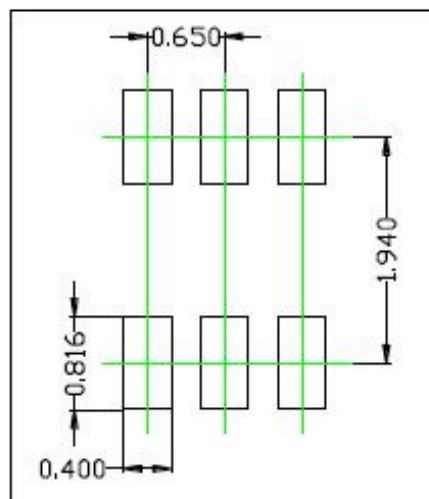
TOP VIEW



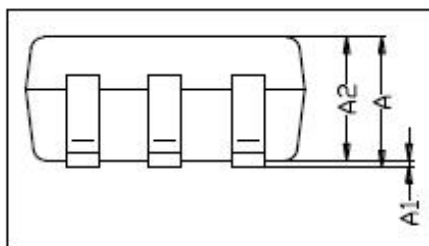
SIDE VIEW



SOLDERING PATTERN



FRONT VIEW



SYMBOL	DIMENSIONS IN MILLIMETER	
	MIN	MAX
A	0.900	1.000
A1	0.000	0.100
A2	0.900	1.000
b	0.150	0.300
c	0.100	0.150
D	2.000	2.200
E	1.150	1.350
E1	2.150	2.400
e	0.650 TYP.	
e1	1.200	1.400
L	0.525 REF.	
L1	0.260	0.450
θ	0°	8°



DISCLAIMER

SSCSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. SSCSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENCE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

THE GRAPHS PROVIDED IN THIS DOCUMENT ARE STATISTICAL SUMMARIES BASED ON A LIMITED NUMBER OF SAMPLES AND ARE PROVIDED FOR INFORMATIONAL PURPOSE ONLY. THE PERFORMANCE CHARACTERISTICS LISTED IN THEM ARE NOT TESTED OR GUARANTEED. IN SOME GRAPHS, THE DATA PRESENTED MAY BE OUTSIDE THE SPECIFIED OPERATING RANGE (E.G. OUTSIDE SPECIFIED POWER SUPPLY RANGE) AND THEREFORE OUTSIDE THE WARRANTED RANGE.

OUR PRODUCT SPECIFICATIONS ARE ONLY VALID IF OBTAINED THROUGH THE COMPANY'S OFFICIAL WEBSITE, CRM SYSTEM, OR OUR SALES PERSONNEL CHANNELS. IF CHANGES OR SPECIAL VERSIONS ARE INVOLVED, THEY MUST BE STAMPED WITH A QUALITY SEAL AND MARKED WITH A SPECIAL VERSION NUMBER TO BE VALID.